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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Features

- $BV_{CEO} > -12V$
- $I_C = -3A$ Continuous Current
- $I_{CM} = -10A$ Peak Pulse Current
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

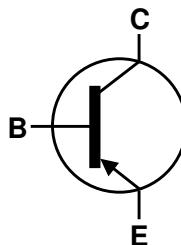
Mechanical Data

- Case: SOT223
- Case Material: Molded Plastic. "Green" Molding Compound; UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads; Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.112 grams (Approximate)

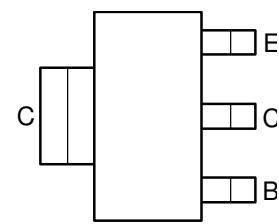
SOT223



Top View



Device Symbol


Top View
Pin-Out

Ordering Information (Note 4)

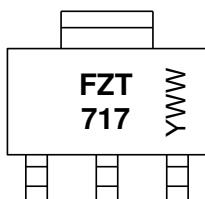
Product	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
FZT717TA	AEC-Q101	FZT717	7	12	1,000

Notes:

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-Free, "Green" and Lead-Free.
3. Halogen- and Antimony-Free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information

SOT223



FZT 717 = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 5= 2015)
 WW or \bar{WW} = Week Code (01~53)

Absolute Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-12	V
Collector-Emitter Voltage	V_{CEO}	-12	V
Emitter-Base Voltage	V_{EBO}	-7	V
Continuous Collector Current	I_C	-3	A
Peak Pulse Current	I_{CM}	-10	A
Base Current	I_B	-500	mA

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation	P_D	3.0	W
		2.0	
		1.6	
		1.2	
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	41.7	°C/W
		62.5	
		78.1	
		104	
Thermal Resistance, Junction to Leads	$R_{\theta JL}$	12.9	°C/W
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	°C

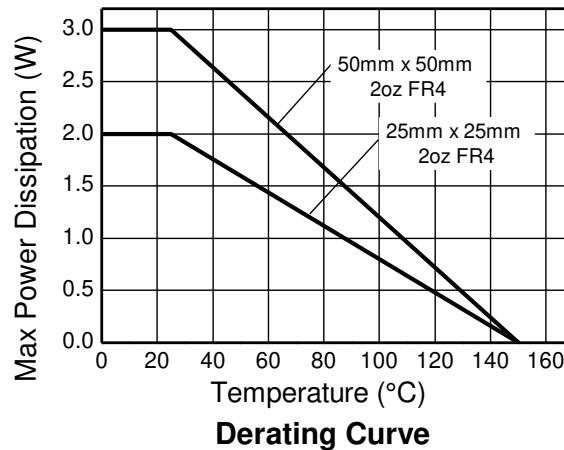
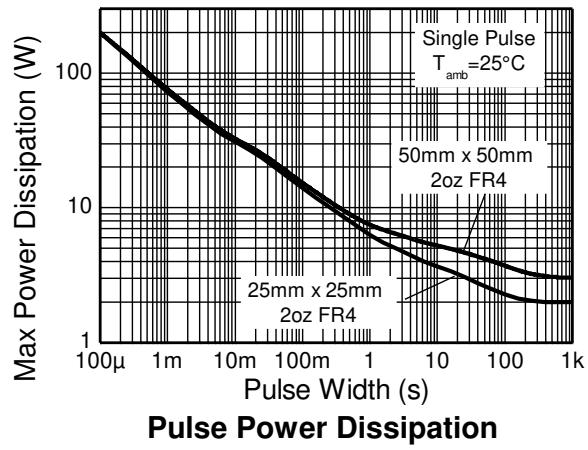
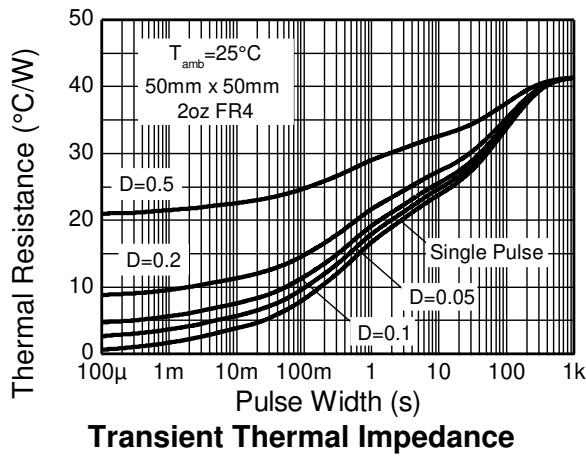
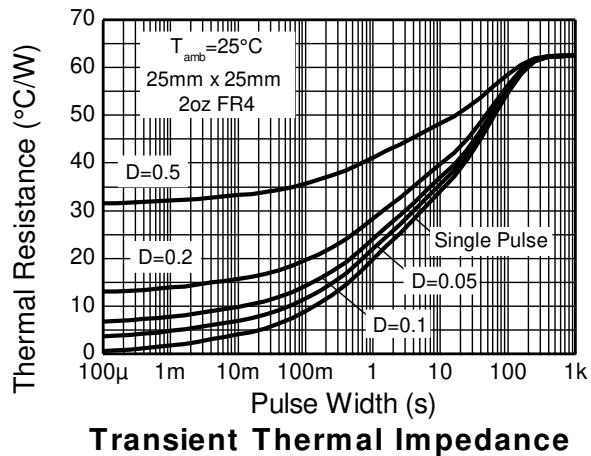
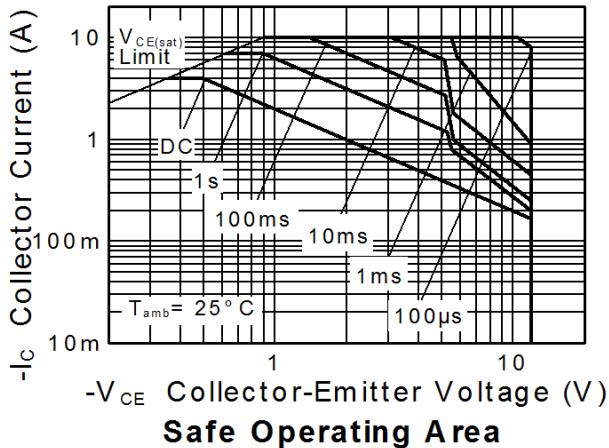
ESD Ratings (Note 10)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:

5. For a device mounted with the collector lead on 50mm x 50mm 2oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
6. Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper.
7. Same as Note 5, except the device is mounted on 25mm x 25mm 1oz copper.
8. Same as Note 5, except the device is mounted on minimum recommended pad layout.
9. Thermal resistance from junction to solder-point (at the end of the collector lead).
10. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

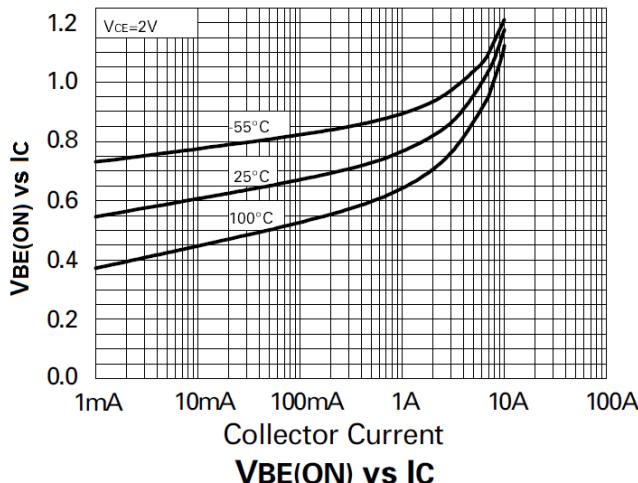
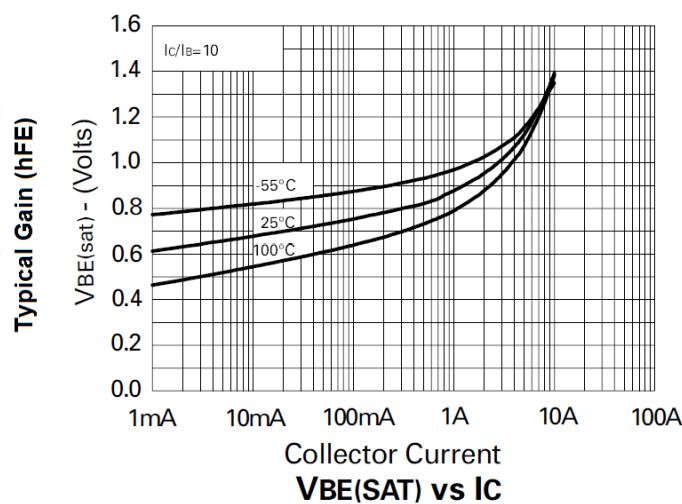
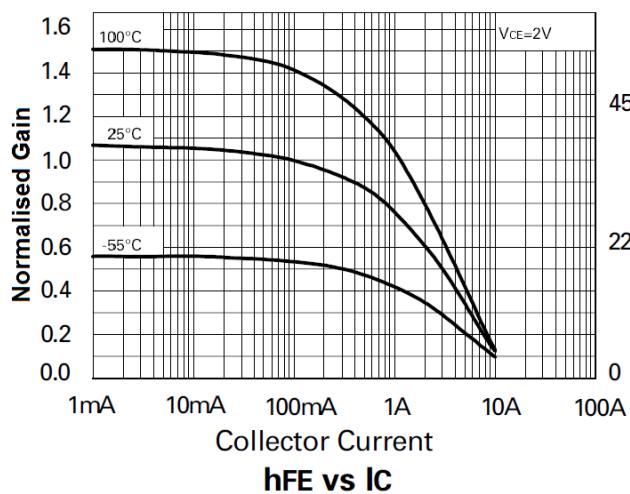
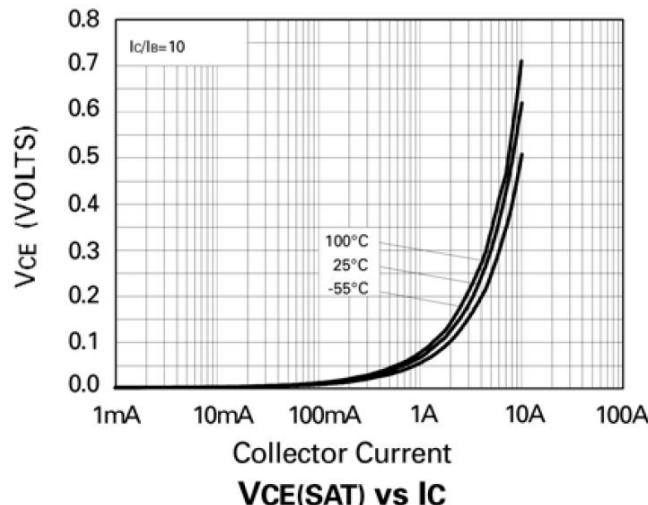
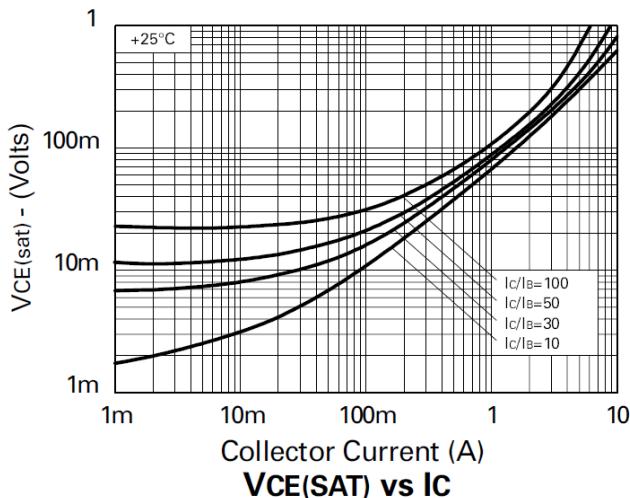


Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV_{CBO}	-12	—	—	V	$I_C = -100\mu\text{A}$
Collector-Emitter Breakdown Voltage (Note 11)	BV_{CEO}	-12	—	—	V	$I_C = -10\text{mA}$
Emitter-Base Breakdown Voltage	BV_{EBO}	-7	—	—	V	$I_E = -100\mu\text{A}$
Collector Cut-Off Current	I_{CBO}	—	<1	-100	nA	$V_{\text{CB}} = -10\text{V}$
Emitter Cut-Off Current	I_{EBO}	—	<1	-100	nA	$V_{\text{EB}} = -4\text{V}$
Collector-Emitter Saturation Voltage (Note 11)	$V_{\text{CE}(\text{sat})}$	—	—	-20	mV	$I_C = -100\text{mA}, I_B = -10\text{mA}$
				-150		$I_C = -1\text{A}, I_B = -10\text{mA}$
				-320		$I_C = -3\text{A}, I_B = -50\text{mA}$
Base-Emitter Saturation Voltage (Note 11)	$V_{\text{BE}(\text{sat})}$	—	—	-1.05	V	$I_C = -3\text{A}, I_B = -50\text{mA}$
Base-Emitter Turn-On Voltage (Note 11)	$V_{\text{BE}(\text{on})}$	—	—	-1.0	V	$I_C = -3\text{A}, V_{\text{CE}} = -2\text{V}$
DC Current Gain (Note 11)	h_{FE}	300	—	—		$I_C = -10\text{mA}, V_{\text{CE}} = -2\text{V}$
		300				$I_C = -100\text{mA}, V_{\text{CE}} = -2\text{V}$
		160				$I_C = -3\text{A}, V_{\text{CE}} = -2\text{V}$
		60				$I_C = -8\text{A}, V_{\text{CE}} = -2\text{V}$
		45				$I_C = -10\text{A}, V_{\text{CE}} = -2\text{V}$
Current Gain-Bandwidth Product	f_T	80	110	—	MHz	$I_C = -50\text{mA}, V_{\text{CE}} = -10\text{V}, f = 100\text{MHz}$
Output Capacitance	C_{obo}	—	21	30	pF	$V_{\text{CB}} = -10\text{V}, f = 1\text{MHz}$
Switching Times	t_{on}	—	70	—	ns	$I_C = -2\text{A}, V_{\text{CC}} = -6\text{V}, I_{B1} = I_{B2} = 50\text{mA}$
	t_{off}		130			

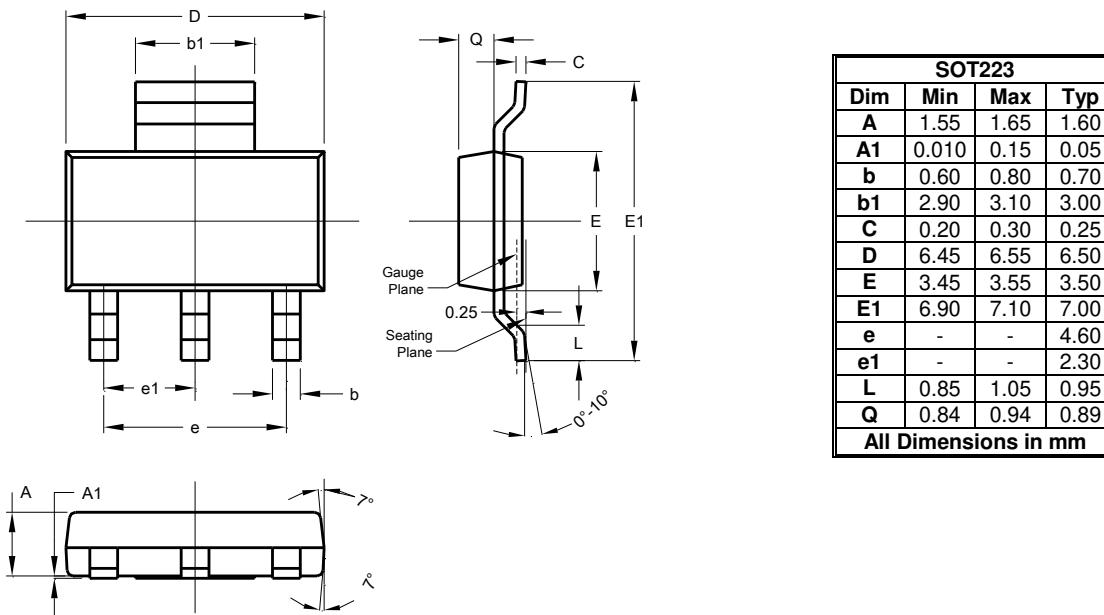
Note: 11. Measured under pulsed conditions. Pulse width $\leq 300\text{ }\mu\text{s}$. Duty cycle $\leq 2\%$.

Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



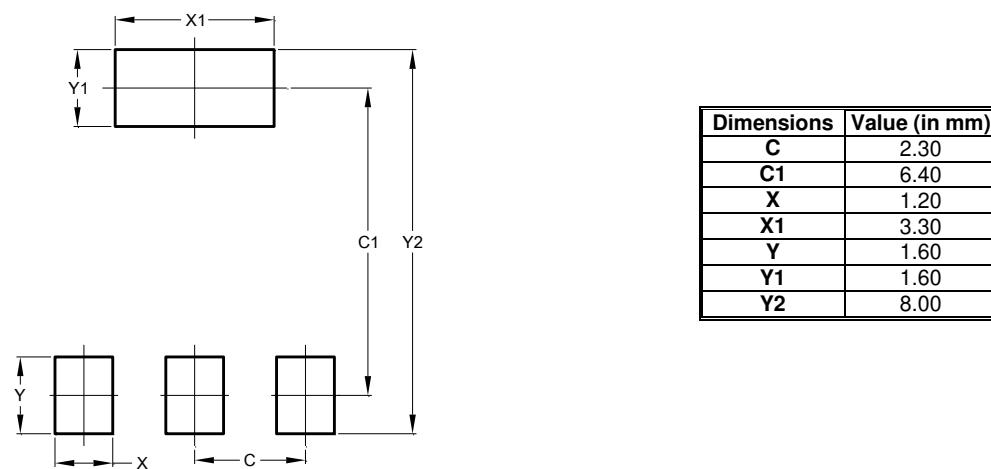
Package Outline Dimensions

Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



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